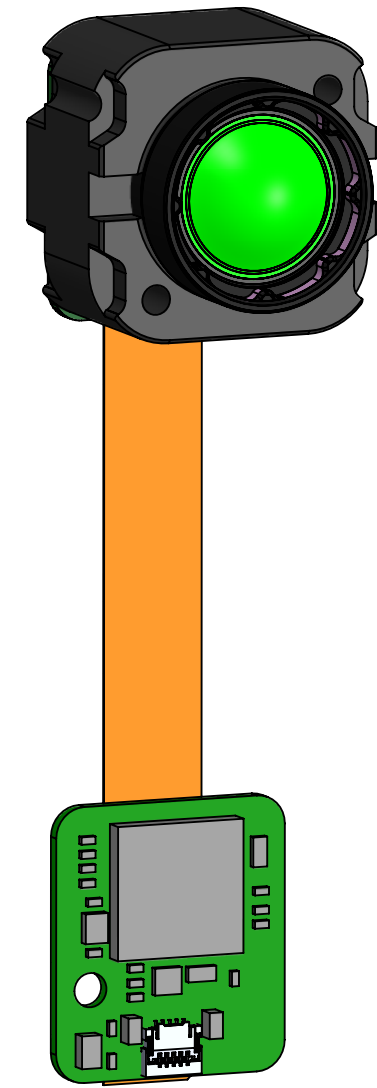
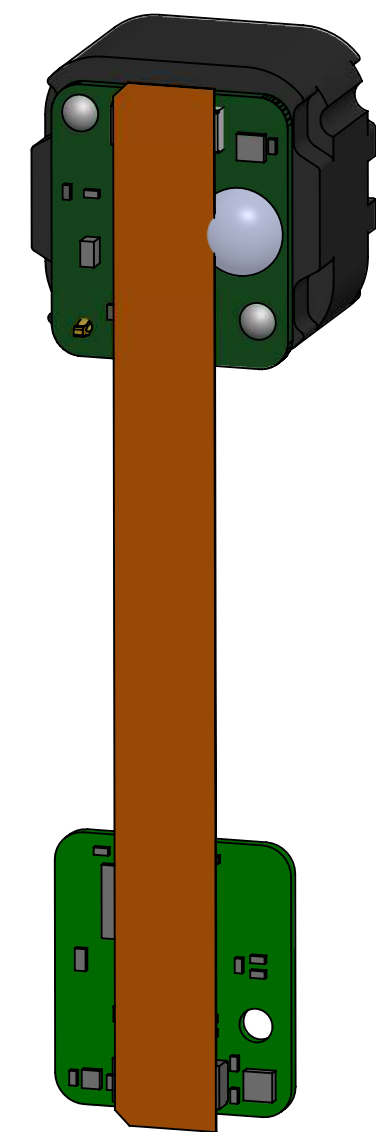
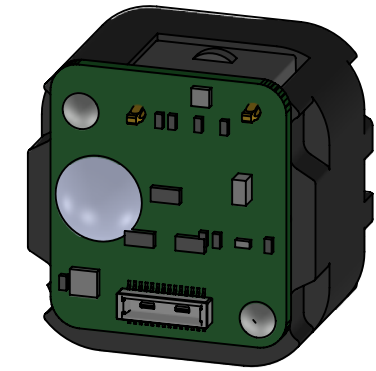
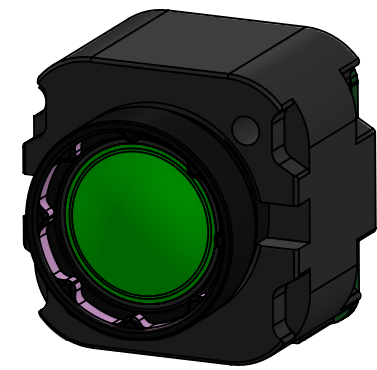


THIS DRAWING COVERS
THE FOLLOWING SKUS:
C2*9*
C3*9*
S2*9*
S3*9*

NO COPROCESSOR BOARD

"P" OPTION WITH COPROCESSOR BOARD



NOTES:

- 1. SEE 3D CAD FILE FOR FULL GEOMETRY.
- 2. THIS DESIGN IS CAPABLE OF BEING IP67 WHEN USED WITH APPROPRIATE SEALING DESIGN. SEE MOSAIC DATASHEET.
- 3. COPROCESSOR BOARD AND FLEX INCLUDED WITH "P" OPTION CORES.

- 2. KEEP-OUT FOR SHUTTER CLEARANCE.
- 3. LENS ADHESIVE DOES NOT EXTEND ABOVE FRONT FACE.
- 5. ADHESIVE BUMP PRESENT ON <9Hz CORES.

MATERIAL	SEE NOTES	DRAWN	DLM	27MAR2019
FINISH	SEE NOTES	APPR.		
UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MM (IN) IN ACCORDANCE WITH ASME Y14.5-2009		THIRD ANGLE PROJECTION		
GENERAL TOLERANCES 0.5 TO 6 ±0.1 [.004] > 6 TO 30 ±0.2 [.008] > 30 TO 120 ±0.2 [.008] > 120 TO 400 ±0.3 [.012] ANGLES ±1°		THE INFORMATION CONTAINED IN THIS DRAWING IS THE SOLE PROPERTY OF SEEK THERMAL. ANY REPRODUCTION IN PART OR AS A WHOLE WITHOUT WRITTEN PERMISSION IS PROHIBITED.		

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TITLE: DOC, INTERFACE CONTROL
DRAWING, MECH, 9.1MM MOSAIC

SIZE	DWG. NO.	REV
B	DOC_247	3

SCALE: 2:1 SHEET 1 OF 2

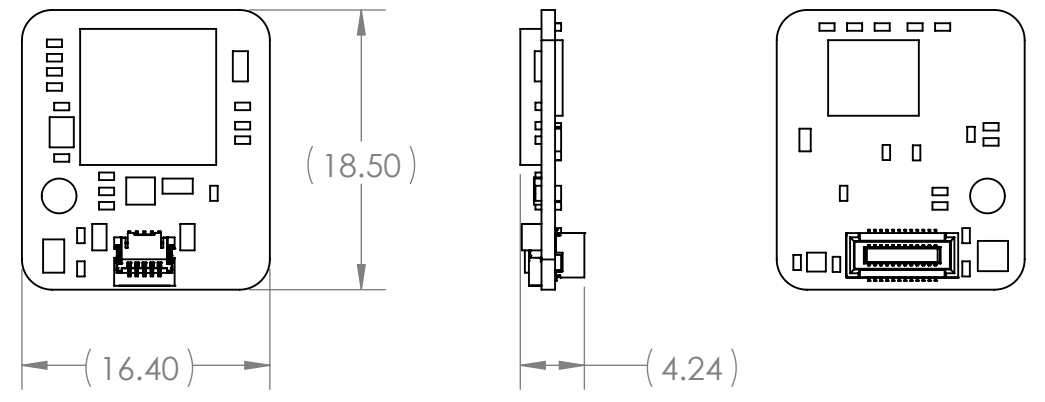
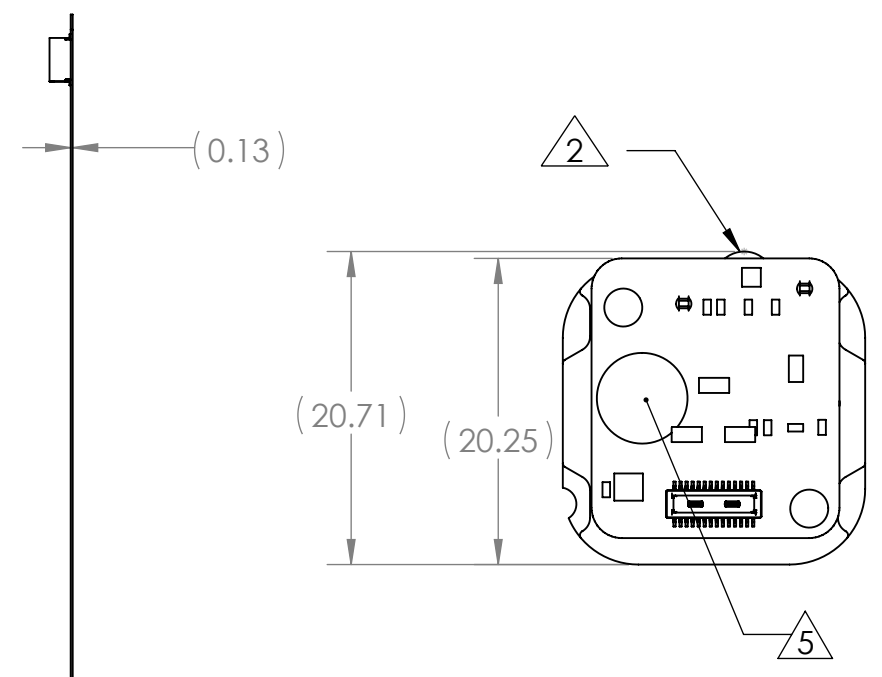
8 7 6 5 4 3 2 1

D
C
B
A

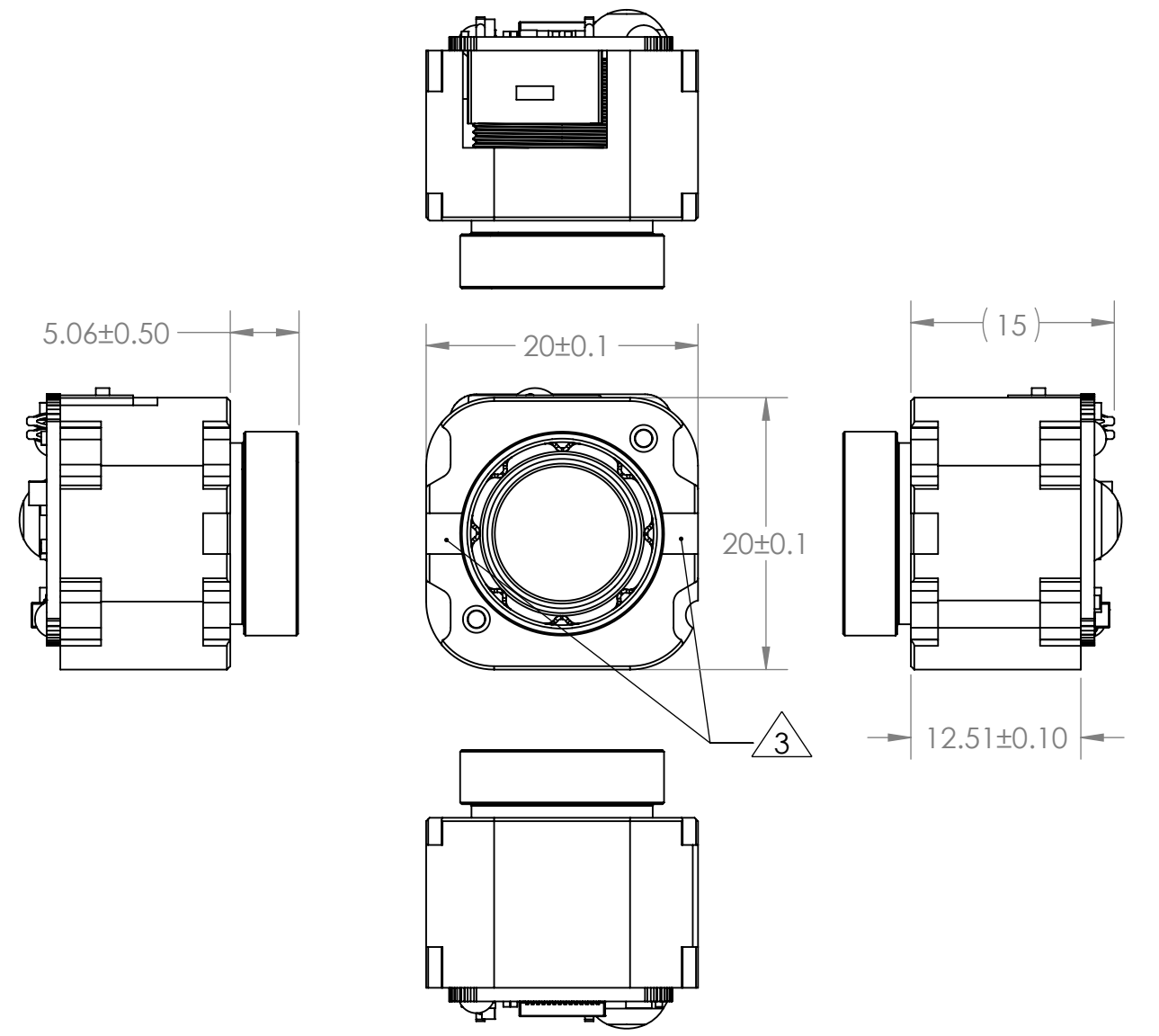
D
C
B
A



FLEX CABLE



COPROCESSOR BOARD



THERMAL IMAGING CORE

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TITLE: DOC, INTERFACE CONTROL
DRAWING, MECH, 9.1MM MOSAIC

SIZE	DWG. NO.	REV
B	DOC_247	3
SCALE: 2:1		SHEET 2 OF 2

8 7 6 5 4 3 2 1